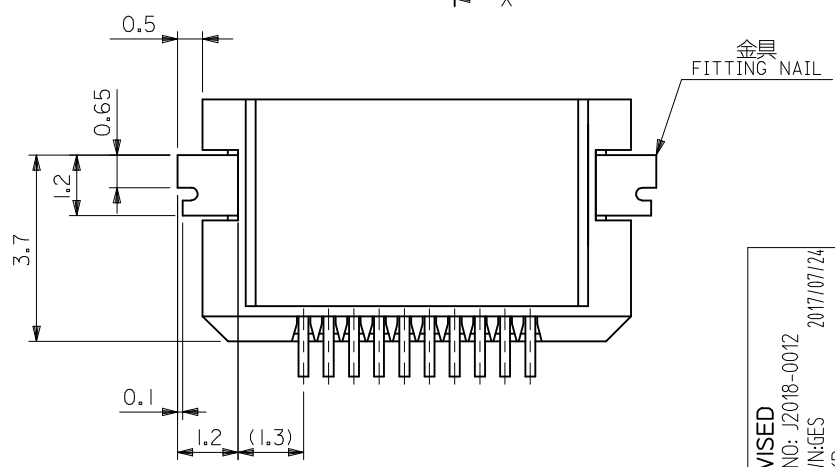
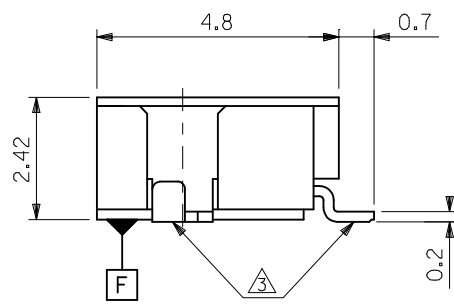
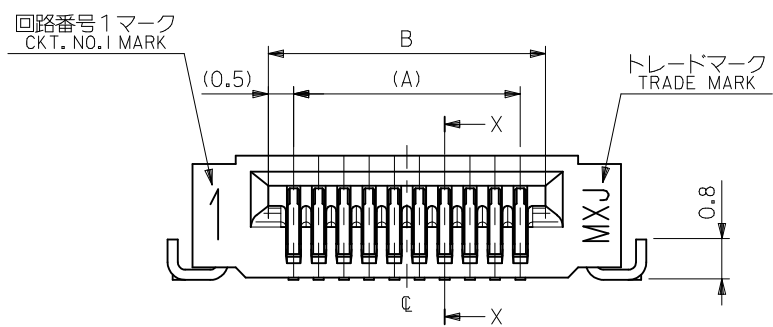


注記 NOTES

- 材質 MATERIAL  
 ハウジング: PPS, UL94V-0  
 HOUSING: PPS, UL94V-0  
 ターミナル: リン青銅 (t=0.2)、ニッケル下地 錫ビスマスメッキ  
 TERMINAL: PHOS-BRO.(t=0.2), TIN-BIMUSTH OVER NICKEL PLATING  
 金具: リン青銅 (t=0.2)、ニッケル下地 錫メッキ  
 FITTING NAIL: PHOS-BRO.(t=0.2), TIN OVER NICKEL PLATING  
 HARF BRIGHT PLATING  
 △ 偶数極に適用。  
 APPLY FOR EVEN CIRCUIT.  
 △ ソルダータール半田付け面及び金具半田付け面のズレ量は、基準面 F に対し、上方向 0.1 MAX. 下方向 0.15 MAX. とする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM F : UPPER DIRECTION 0.1 MAX. : LOWER DIRECTION 0.15 MAX.
- 本製品は 52976-\*\*-40 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52976-\*\*-40



18.5	15.5	14.5	52976-3072	52976-3049	30
15.5	12.5	11.5	-2472	-2449	24
12.5	9.5	8.5	-1872	-1849	18
11.5	8.5	7.5	-1672	-1649	16
8.5	5.5	4.5	-1072	-1049	10
8.0	5.0	4.0	-0972	-0949	9
7.5	4.5	3.5	52976-0872	52976-0849	8

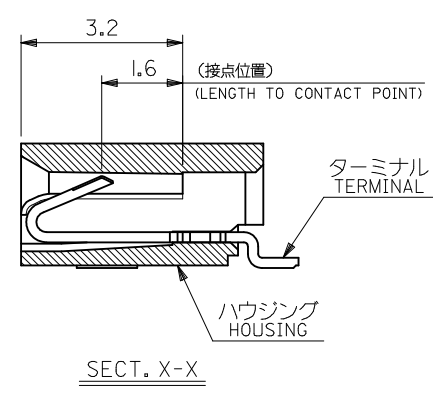
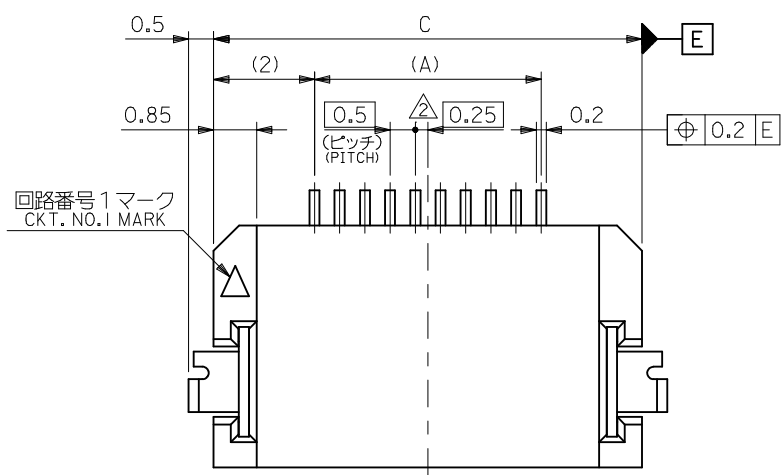
52976-\*\*-49 MODEL NO.

REVISED EC NO: J2018-0012 DRAWINGS CHKD: APPR: MSASAO 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER ± 0.25 OVER 0.5 UNDER ± 0.5 OVER 1.0 UNDER ± 0 OVER 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 °	MM ONLY	---	METRIC	
	DRAWN BY HSHIMABUKURO CHECKED BY K. TOJO APPROVED BY M. SASAO MATERIAL NO.	DATE '04/03/01 DATE '04/03/01 DATE '04/03/01	TITLE	EMBOSSED TAPE PKG. ORDER No. オーダー番号	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE SIZE A3	MATERIAL NO. DOCUMENT NO. SD-52976-010 SHEET NO. 1 OF 2	

0.5 FFC/FPC CONN NON-ZIF HSG ASSY(BOTTOM CONTACT) -LEAD FREE-

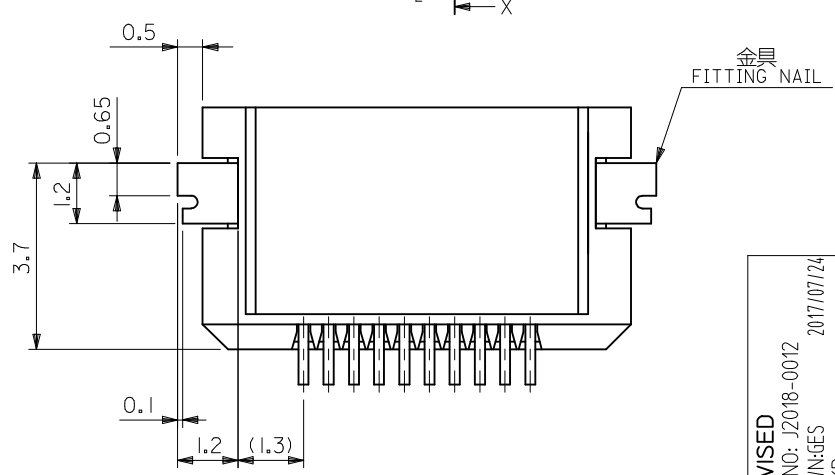
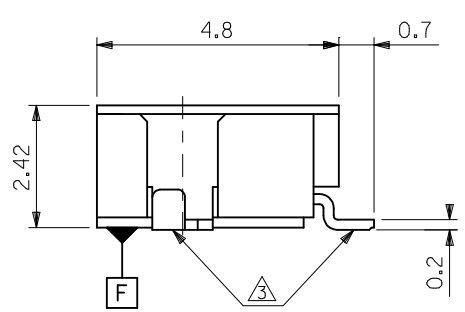
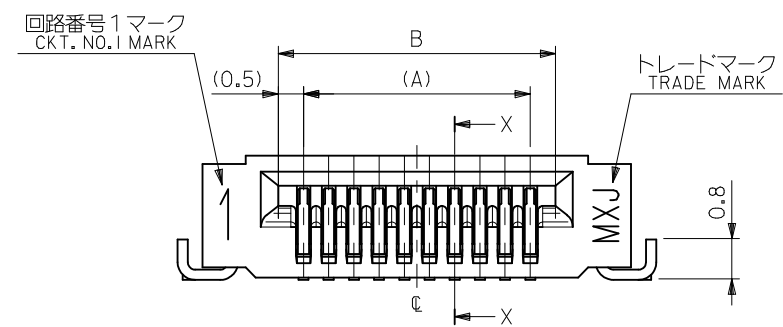


THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



注記 NOTES

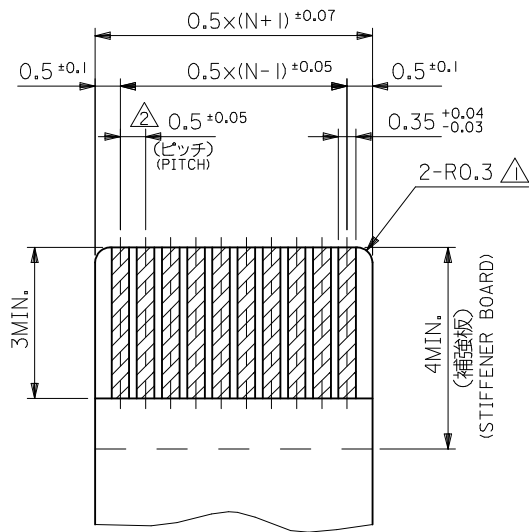
- 材質 MATERIAL  
 ハウジング: PPS, UL94V-0  
 HOUSING: PPS, UL94V-0  
 ターミナル: リン青銅 (t=0.2)、ニッケル下地 錫ビスマスメッキ  
 TERMINAL: PHOS-BRO.(t=0.2), TIN-BIMUSTH OVER NICKEL PLATING  
 金具: リン青銅 (t=0.2)、ニッケル下地 錫メッキ  
 FITTING NAIL: PHOS-BRO.(t=0.2), TIN OVER NICKEL PLATING  
 HARF BRIGHT PLATING  
 △ 偶数極に適用。  
 APPLY FOR EVEN CIRCUIT.  
 △ ソルダータール半田付け面及び金具半田付け面のズレ量は、基準面 F に対し、上方向 0.1 MAX. 下方向 0.15 MAX. とする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM F : UPPER DIRECTION 0.1 MAX. : LOWER DIRECTION 0.15 MAX.
- 本製品は 52976-\*\*-40 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 52976-\*\*-40



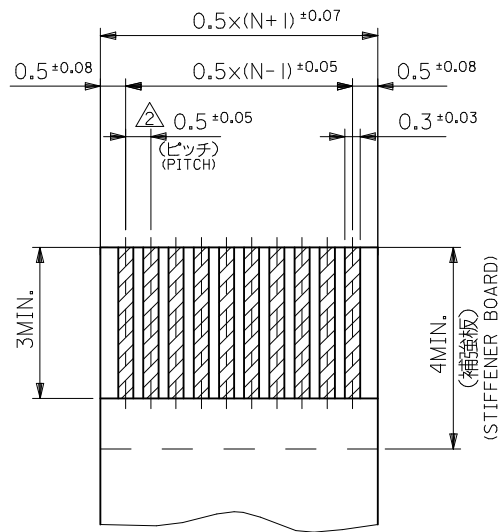
18.5	15.5	14.5	52976-3072	52976-3049	30
15.5	12.5	11.5	-2472	-2449	24
12.5	9.5	8.5	-1872	-1849	18
11.5	8.5	7.5	-1672	-1649	16
8.5	5.5	4.5	-1072	-1049	10
8.0	5.0	4.0	-0972	-0949	9
7.5	4.5	3.5	52976-0872	52976-0849	8

52976-\*\*-49 MODEL NO.

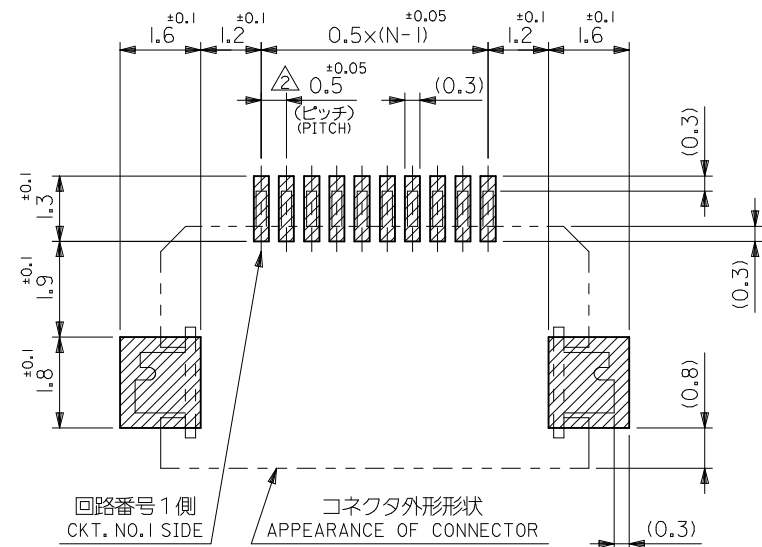
REVISED EC NO: J2018-0012 DRAWNGES CHKD: APPR:MSASAO 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER ± 0.25 OVER 0.5 UNDER ± 0.5 OVER 1.0 UNDER ± 0 OVER 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 °	MM ONLY	---	METRIC	
	DRAWN BY HSHIMABUKURO CHECKED BY K.TOJO APPROVED BY M.SASAO DATE '04/03/01 DATE '04/03/01 DATE '04/03/01	TITLE			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	0.5 FFC/FPC CONN NON-ZIF HSG ASSY(BOTTOM CONTACT) -LEAD FREE- <b>molex</b> DOCUMENT NO. SD-52976-010 SHEET NO. 1 OF 2		



適合FPC推奨寸法  
 APPLICABLE FPC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)



適合FFC推奨寸法  
 APPLICABLE FFC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)



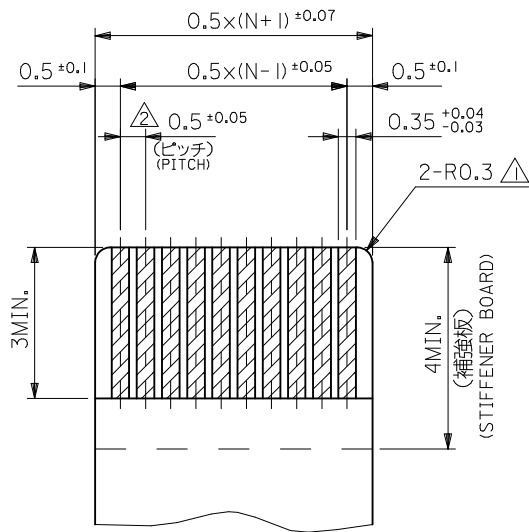
参考基板レイアウト  
 REFERENCE P.C.BOARD  
 PATTERN DIMENSION  
 (マウント面)  
 (MOUNTING SIDE)

注記 NOTES

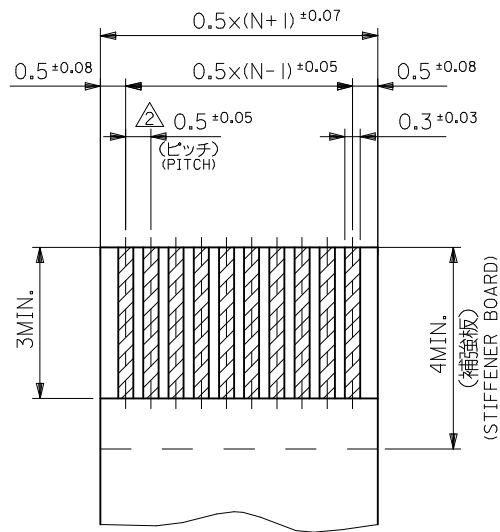
- △ R0.3 は、FPCの導体部にかからないこと。  
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- △ 公差非累積のこと。  
 NON-ACCUMULATIVE.
- 3. FPCについて:  
 打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER FILM: POLYIMIDE  
 BONDING AGENT: THERMOSETTING BONDING AGENT

52976-\*\*\*49 MODEL NO.

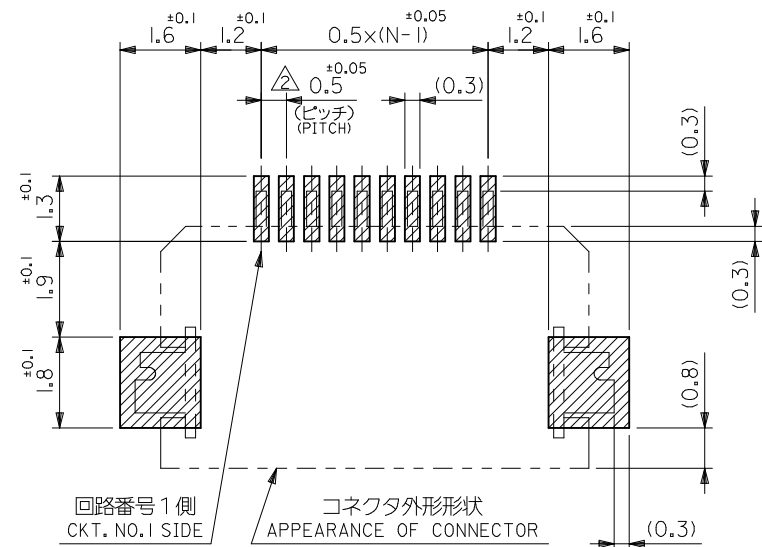
REVISED EC NO: J2018-0012 DRAWN: MSASAO CHKD: MSASAO APPR: MSASAO 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		---	METRIC	□
	0.25 UNDER	±	DRAWN BY	DATE	TITLE		
	0.25 OVER	±	HS HIMABUKURO	'04/03/01	0.5 FFC/FPC CONN NON-ZIF HSG ASSY(BOTTOM CONTACT) -LEAD FREE-		
0.5 OVER	±	CHECKED BY	DATE	DRAWN BY			DOCUMENT NO.
0 OVER	±	K. TOJO	'04/03/01	DATE			
10 OVER	±0.2	APPROVED BY	DATE	MATERIAL NO.			SHEET NO.
30 OVER	±0.25	M. SASAO	'04/03/01	DATE			
ANGULAR	±3 °	SEE SHEET 1		SD-52976-010			2 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				A3			



適合FPC推奨寸法  
 APPLICABLE FPC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)



適合FFC推奨寸法  
 APPLICABLE FFC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)



参考基板レイアウト  
 REFERENCE P.C.BOARD  
 PATTERN DIMENSION  
 (マウント面)  
 (MOUNTING SIDE)

注記 NOTES

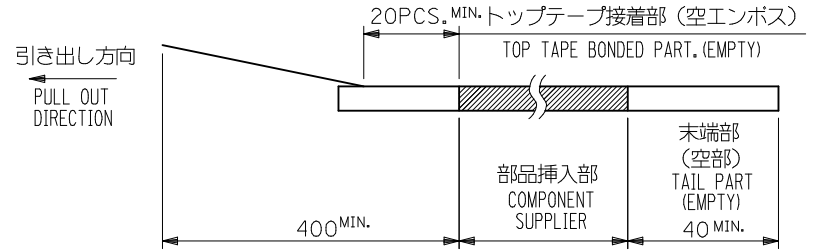
- △ R0.3 は、FPCの導体部にかからないこと。  
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- △ 公差非累積のこと。  
 NON-ACCUMULATIVE.
- 3. FPCについて:  
 打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

52976-\*\*\*49 MODEL NO.

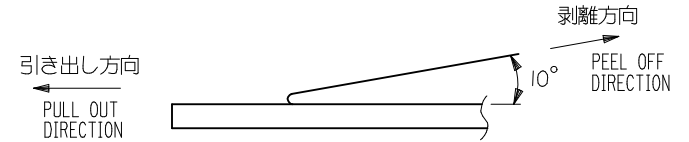
REVISED EC NO: J2018-0012 DRAWN: MSASAO CHKD: MSASAO APPR: MSASAO	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		---	METRIC	□
	0.25 UNDER	±	DRAWN BY	DATE	TITLE		
	0.25 OVER	±	HSHIMABUKURO	'04/03/01	0.5 FFC/FPC CONN NON-ZIF HSG ASSY(BOTTOM CONTACT) -LEAD FREE-		
0.5 OVER	±	CHECKED BY	DATE	molex			
1.0 UNDER	±	K. TOJO	'04/03/01				
0 OVER	±0.2	APPROVED BY	DATE	DOCUMENT NO.	SHEET NO.		
10 OVER	±0.25	M. SASAO	'04/03/01	SD-52976-010	2 OF 2		
30 OVER	±0.3	MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	±3 °	SIZE	A3				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

NOTES

1. 梱包数量：1000個/リール  
NUMBER OF CONNECTORS : 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

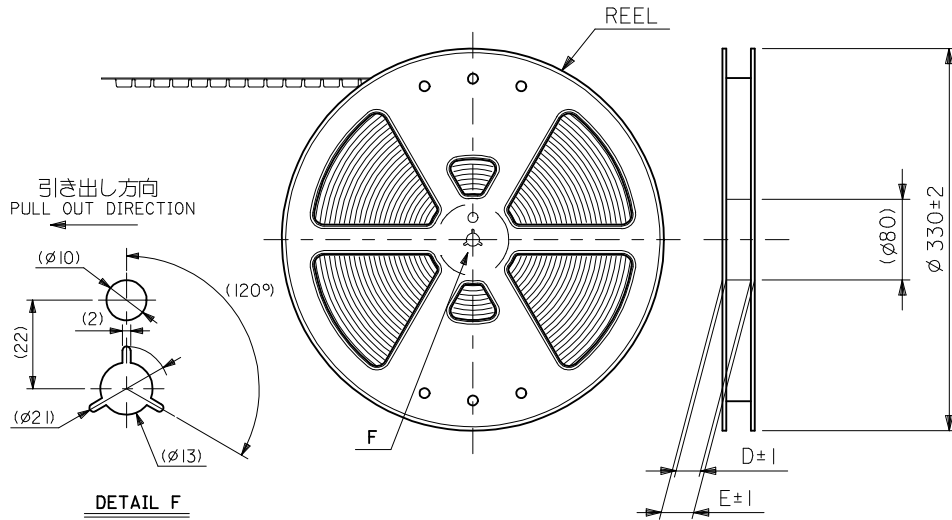


3. トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)  
(剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



4. 材料  
キャリアテープ：ポリプロピレン (PP)  
トップテープ：PET, PE, PEF  
リール：ポリスチレン (PS) <リサイクル材を含む>  
MATERIAL CARRIER TAPE:POLYPROPYLENE  
TOP TAPE:PET,PE,PEF  
REEL:POLYSTYREN(PS)  
<RECYCLE MATERIAL CONTAINED>

5. 本製品は 52976-\*\*-92 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52976-\*\*-92



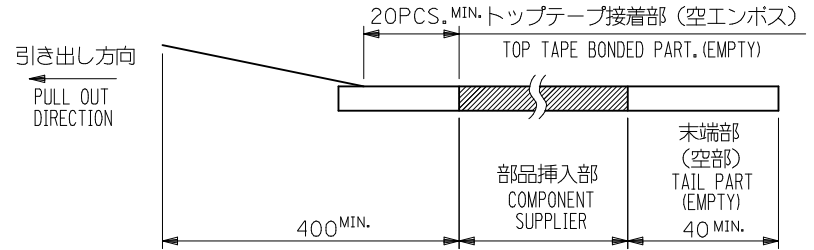
DETAIL F

52976-\*\*-72 MODEL NO.

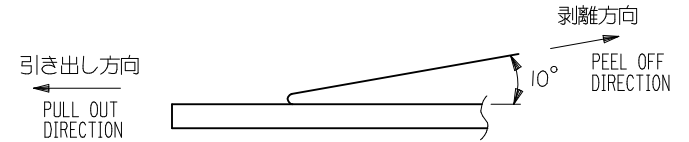
REVISED EC NO: J2018-0012 DRAWINGS CHKD: APPR:MSASAO 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±	H. SHIMABUKUR	2004/03/01	0.5 FPC CONN NON ZIF HOUSING ASSY EMBSTP PKG -LEAD FREE-		
	0.5 OVER 1.0 UNDER	±	CHECKED BY	DATE	molex		
0 OVER 10 UNDER	±0.2	K. TOJO	2004/03/01				
10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.	
30 OVER	±0.3	M. SASAO	2004/03/01	SD-52976-011		1 OF 2	
ANGULAR	±3 °	MATERIAL NO.		SEE SHEET 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

1. 梱包数量：1000個/リール  
NUMBER OF CONNECTORS : 1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH

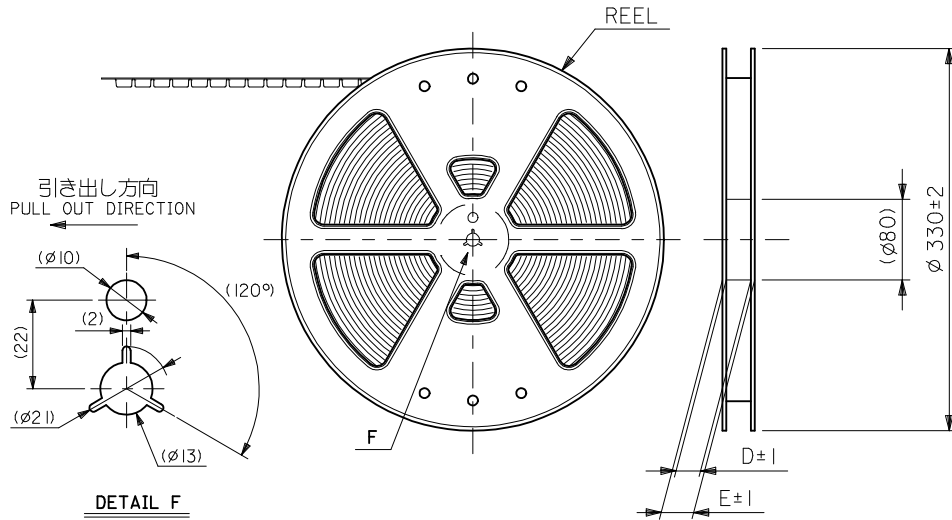


3. トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)  
(剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



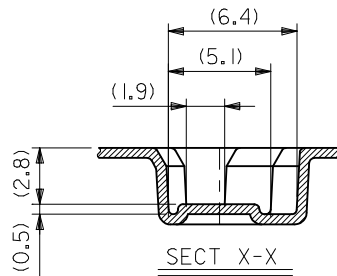
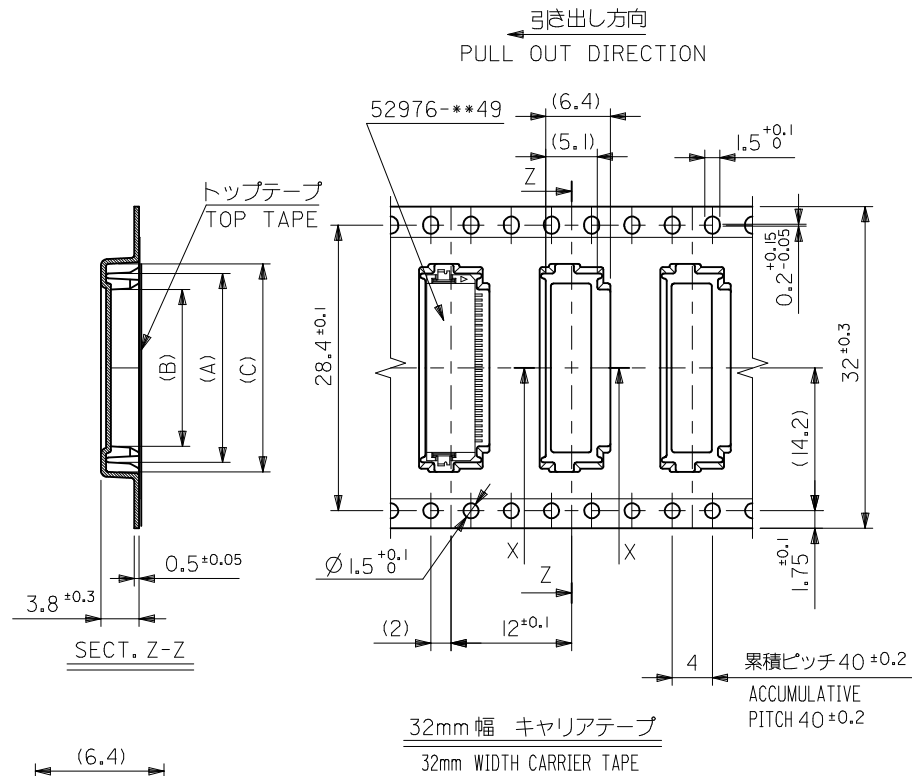
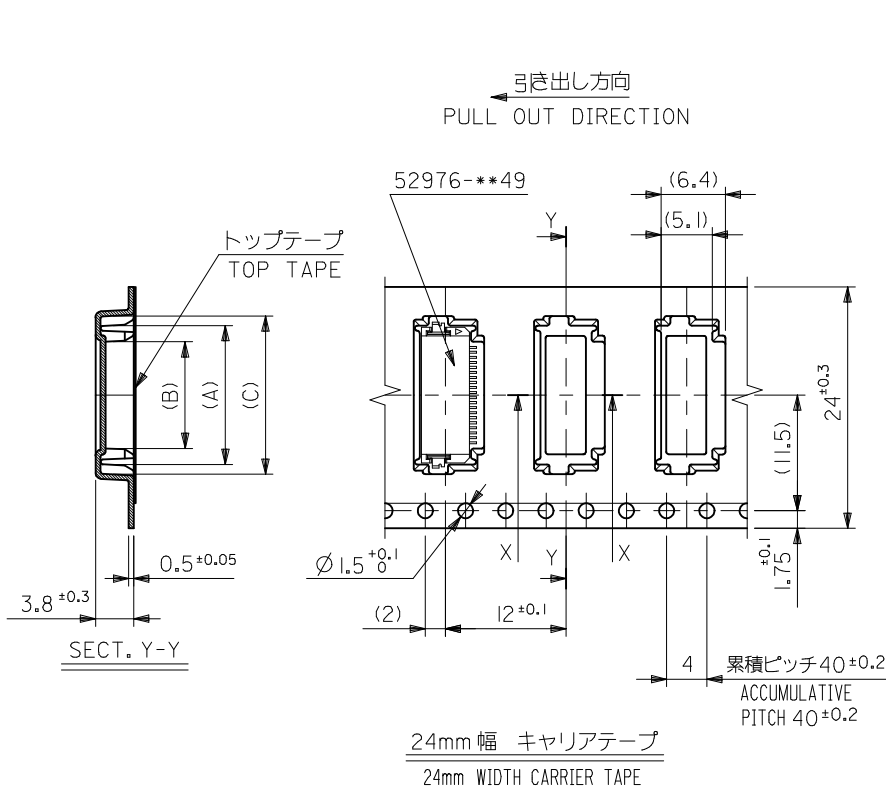
4. 材料  
キャリアテープ：ポリプロピレン (PP)  
トップテープ：PET, PE, PEF  
リール：ポリスチレン (PS) <リサイクル材を含む>  
MATERIAL CARRIER TAPE: POLYPROPYLENE  
TOP TAPE: PET, PE, PEF  
REEL: POLYSTYRENE(PS)  
<RECYCLE MATERIAL CONTAINED>

5. 本製品は 52976-\*\*-92 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 52976-\*\*-92



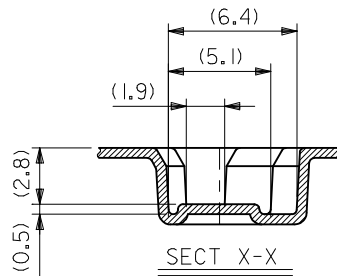
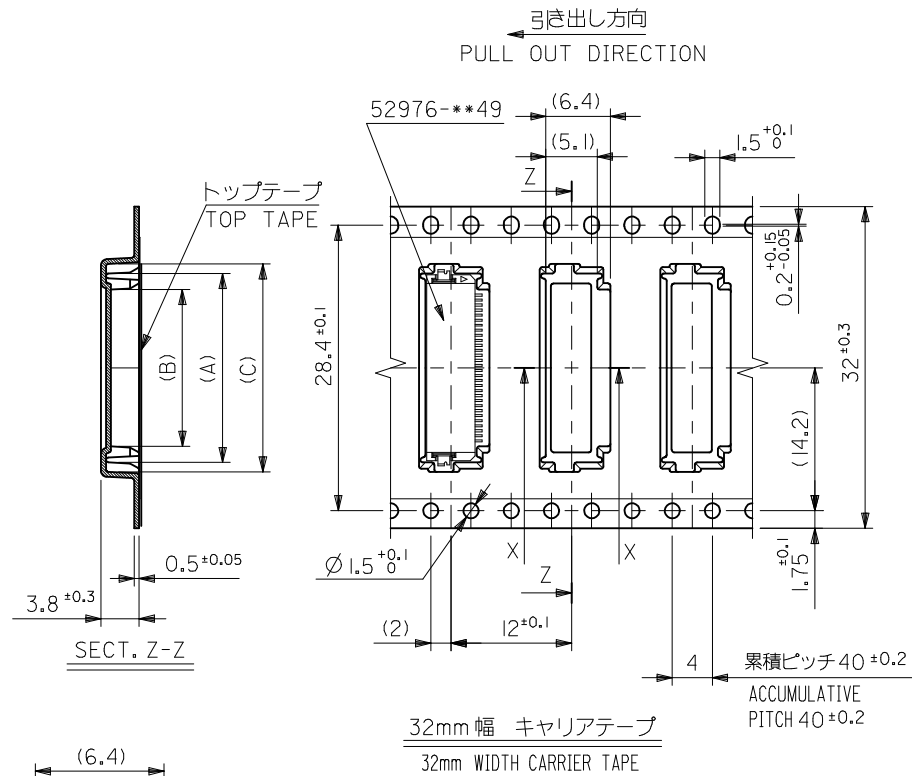
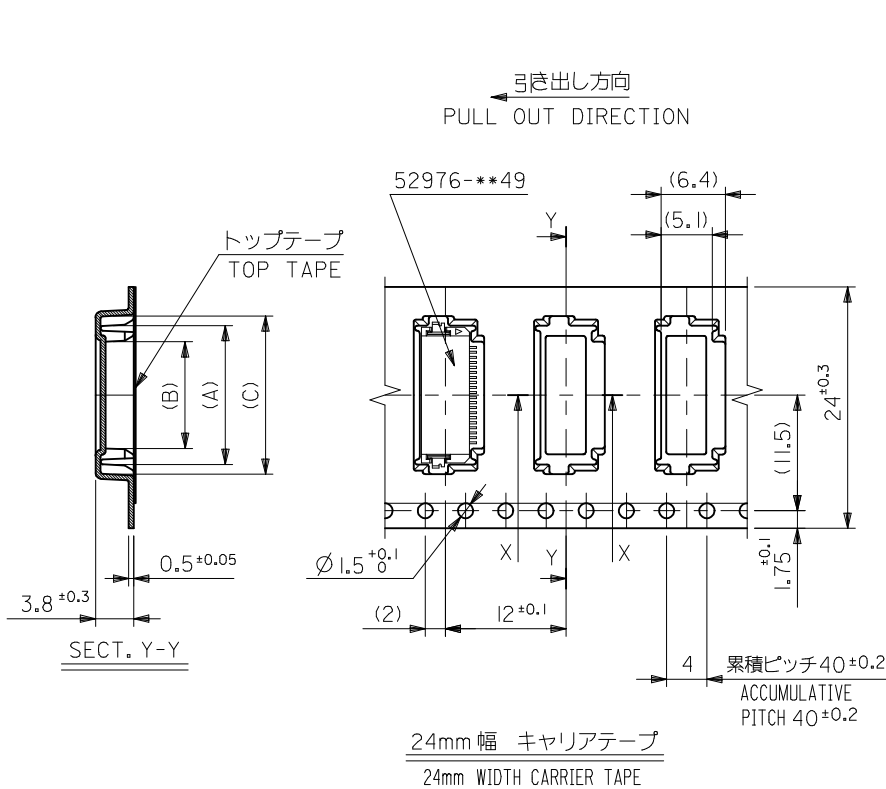
52976-\*\*-72 MODEL NO.

REVISED EC NO: J2018-0012 DRAWINGS: 2017/07/24 CHKD: APPR: MSASAO 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER		±	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±	H. SHIMABUKUR	2004/03/01	0.5 FPC CONN NON ZIF HOUSING ASSY EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±	CHECKED BY	DATE	molex		
0 OVER	10 UNDER	±0.2	K. TOJO	2004/03/01	DOCUMENT NO.			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SD-52976-011			
30 OVER		±0.3	M. SASAO	2004/03/01	SHEET NO.			
ANGULAR	±3 °		MATERIAL NO.		1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



32	37.4	33.4	20.7	15.6	18.8	52976-3072	30
24	29.4	25.4	17.7	12.6	15.8	52976-2472	24
			14.7	9.6	12.8	52976-1872	18
			13.7	8.6	11.8	52976-1672	16
			10.7	5.6	8.8	52976-1072	10
			10.2	5.1	8.3	52976-0972	9
			9.7	4.6	7.8	52976-0872	8
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL. NO.	極数 CKT.

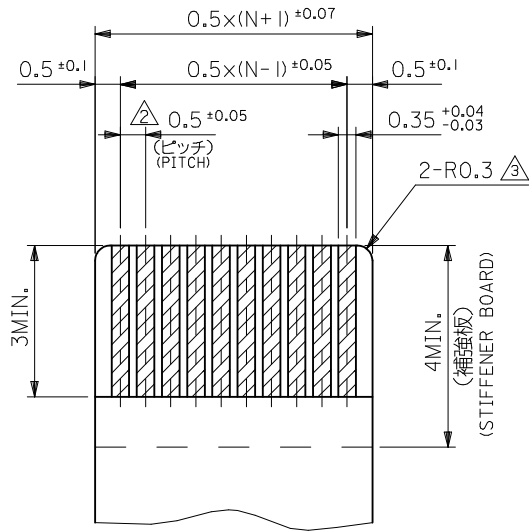
REVISED EC NO: J2018-0012 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	52976-***72 MODEL NO.		
		0.25 UNDER	±	DRAWN BY H. SHIMABUKUR		DATE 2004/03/01	TITLE 0.5 FPC CONN NON ZIF HOUSING ASSY EMBSTP PKG -LEAD FREE-			
		0.25 OVER	0.5 UNDER	±	CHECKED BY K. TOJO		DATE 2004/03/01			
		0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO		DATE 2004/03/01			
10 OVER	30 UNDER	±0.25	MATERIAL NO.		DOCUMENT NO.		SEE TABLE			
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



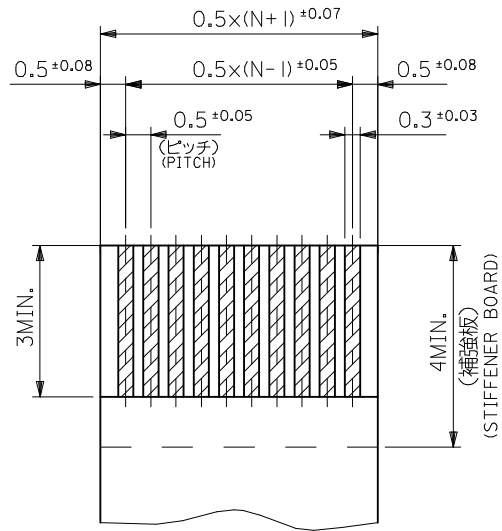
32	37.4	33.4	20.7	15.6	18.8	52976-3072	30
24	29.4	25.4	17.7	12.6	15.8	52976-2472	24
			14.7	9.6	12.8	52976-1872	18
			13.7	8.6	11.8	52976-1672	16
			10.7	5.6	8.8	52976-1072	10
			10.2	5.1	8.3	52976-0972	9
			9.7	4.6	7.8	52976-0872	8
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL. NO.	極数 CKT.

REVISED EC NO: J2018-0012 DRAWINGS CHKD: APPR:MSASAO	DESCRIPTION 2017/07/24 2017/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	±	DRAWN BY H. SHIMABUKUR	DATE 2004/03/01	TITLE 0.5 FPC CONN NON ZIF HOUSING ASSY EMBSTP PKG -LEAD FREE-				
		0.25 OVER	0.5 UNDER	±	CHECKED BY K. TOJO	DATE 2004/03/01				
		0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE 2004/03/01				
10 OVER	30 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
30 OVER	±0.25	SEE TABLE		SD-52976-011		2 OF 2				
ANGULAR		±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

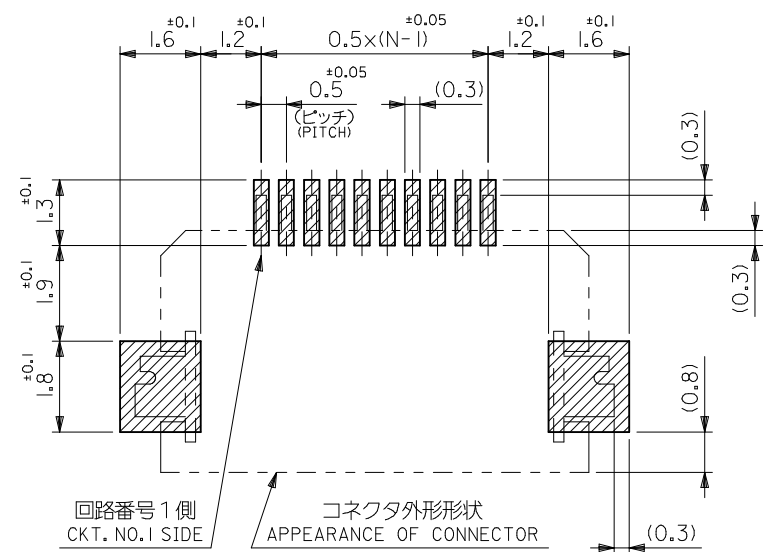




適合FPC推奨寸法  
 APPLICABLE FPC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS : 0.3±0.03)

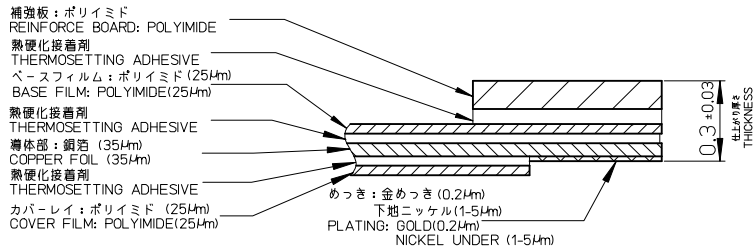


適合FFC推奨寸法  
 APPLICABLE FFC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.3±0.03)  
 (THICKNESS : 0.3±0.03)



推奨基板レイアウト  
 RECOMMENDED P.C. BOARD  
 PATTERN DIMENSION  
 (マウント面)  
 (MOUNTING SIDE)

マスク厚 : 100 μm  
 マスク開口率 : 100%  
 SCREEN THICKNESS : 100MICROMETER  
 SCREEN OPEN RATIO : 100%



FPC構成推奨仕様  
 STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC  
 打ち抜き方向は導体側から補強板側を推奨します。  
 導体部については敷層銅35 μmまたは50 μmを推奨します。  
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE  
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL  
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについてABOUT FPC  
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25 μmを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2013-1133 DRWN: SANUMA 2013/04/11 CHKD: TAKAHASHI 2013/04/11 APP: KMORIKAWA 2013/04/16 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	52976-**-22	MODEL NO.
	10 UNDER	±0.2	DRAWN BY NKONDO	DATE 2012/09/18	TITLE 0.5MM FFC/FPC CONN NON-ZIF HSG ASSY (LOWER CONTACT)		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/18			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-52976-016	SHEET NO. 2 OF 2		
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			